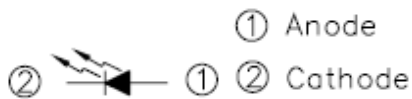
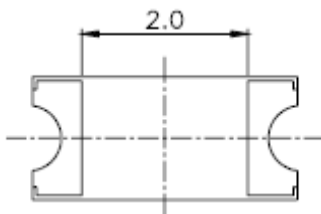
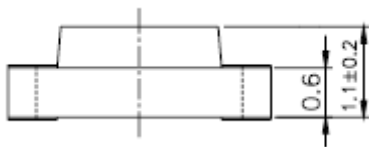
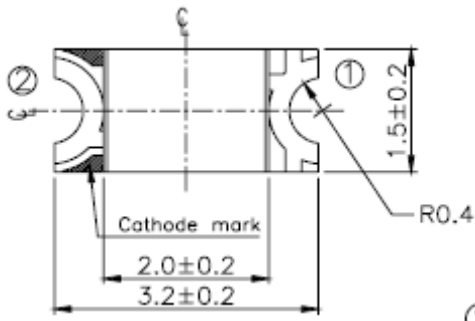


SURFACE MOUNT CHIP LED LAMPS

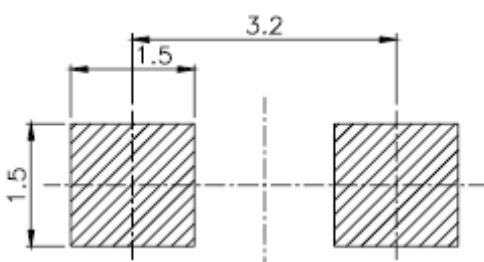
1206 Package Chip Infrared LED

Part Number: IR15-21C/L10

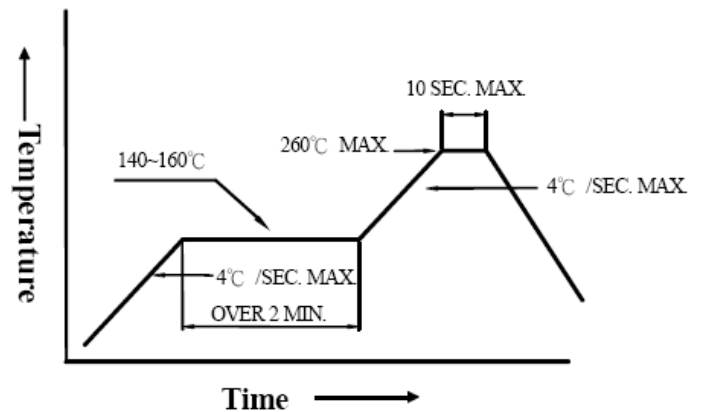
Package outlines & Re-flow Profile



For Reflow Soldering



■Reflow Temp/Time



■Soldering iron

Basic spec is $\leq 5\text{sec}$ when 260°C . If temperature is higher, time should be shorter ($+10^{\circ}\text{C} \rightarrow -1\text{sec}$). Power dissipation of iron should be smaller than 15W, and temperatures should be controllable. Surface temperature of the device should be under 230°C .

| ITEM | MATERIALS |
|-----------------------|-------------|
| Resin (mold) | Epoxy |
| Lens color | Water Clear |
| Printed circuit board | BT |
| Dice | GaAlAs |
| Emitted color | Infrared |

NOTES:

1. All dimensions are in millimeters (inches);
2. Tolerances are $\pm 0.1\text{mm}$ (0.004inch) unless otherwise noted.

SURFACE MOUNT CHIP LED LAMPS

Part Number: IR15-21C/L10

ELECTRO-OPTICAL CHARACTERISTICS**(T_A=25°C)**

| Parameter | Test Condition | Symbol | Value | Unit |
|---|----------------------|-----------------|-------|-------|
| Viewing angle at 50% I _v | I _F =10mA | 2θ 1/2 | 160 | Deg |
| Forward voltage (Typ.) | I _F =20mA | V _F | 1.20 | V |
| (Max.) | | | 1.50 | |
| Radiant Intensity (Min.) | I _F =20mA | I _v | 0.20 | mW/sr |
| (Typ.) | | | 0.80 | |
| Wavelength | I _F =20mA | λ _p | 940 | nm |
| Spectral Line Half-Width | I _F =20mA | Δλ | 45 | nm |
| Peak pulsing current (1/10 duty f=1kHz) | | I _{FP} | 1.0 | A |

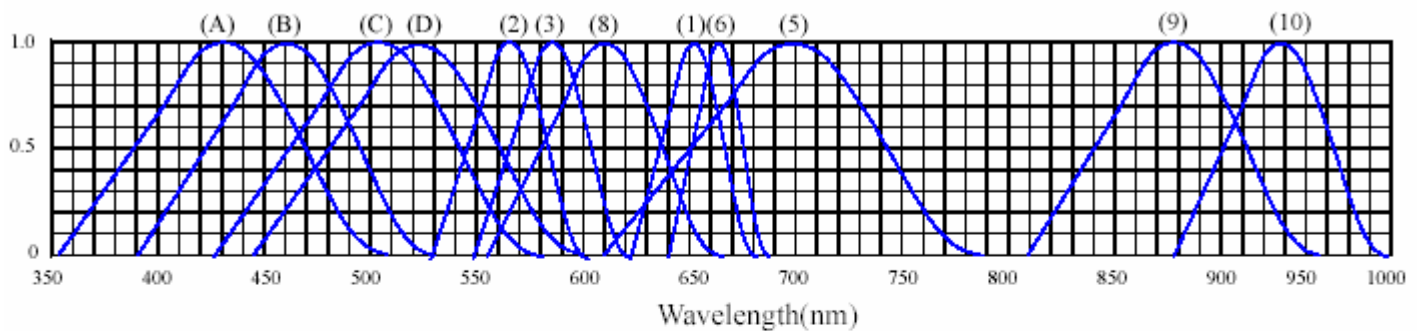
Absolute maximum ratings**(T_A=25°C)**

| Parameter | Symbol | Value | Unit |
|-----------------------------|---------------------|-----------|------|
| Forward current | I _F | 65 | mA |
| Reverse voltage | V _R | 5 | V |
| Reverse current | I _R | 100 | μA |
| Power Dissipation | P _D | 130 | mW |
| Operating temperature range | Top | -25 ~+85 | °C |
| Storage temperature range | Tstg | -40 ~+100 | °C |
| Lead soldering temperature | 260°C For 5 Seconds | | |

SURFACE MOUNT CHIP LED LAMPS**Part Number: IR15-21C/L10****Test items and results of reliability**

| NO. | Item | Test Conditions | Test Hours/ Cycles | Sample Sizes | Failure Judgement Criteria | Ac/Re |
|-----|------------------------------------|--|-----------------------|-----------------|---|-------|
| 1 | REFLOW Soldering | TEMP. : 260°C±5°C 5secs | 6Mins | 22pcs | $I_R \geq U \times 2$ $E_e \leq L \times 0.8$ $V_F \geq U \times 1.2$ U : Upper Specification Limit L : Lower Specification Limit | 0/1 |
| 2 | Temperature Cycle | H : +100°C 15mins ↑ 5mins ↓ L : -40°C 15mins | 50Cycles | 22pcs | | 0/1 |
| 3 | Thermal Shock | H : +100°C 5mins ↑ 10secs ↓ L : -10°C 5mins | 50Cycles | 22pcs | | 0/1 |
| 4 | High Temperature Storage | TEMP. : +100°C | 1000hrs | 22pcs | | 0/1 |
| 5 | Low Temperature Storage | TEMP. : -40°C | 1000hrs | 22pcs | | 0/1 |
| 6 | DC Operating Life | $I_F = 20\text{mA}$ | 1000hrs | 22pcs | | 0/1 |
| 7 | High Temperature/ High Humidity | 85°C / 85% R.H | 1000hrs | 22pcs | | 0/1 |

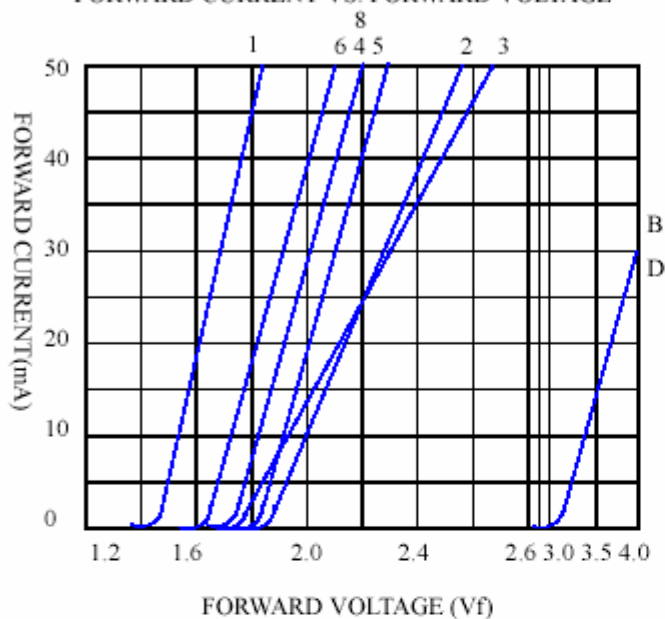
* Refer to reliability test standard specification for in this line.

SURFACE MOUNT CHIP LED LAMPS**Part Number: IR15-21C/L10****Typical Optical-Electrical Characteristic Curves**◆ **TYPICAL ELECTRICAL-OPTICAL CHARACTERISTICS CURVES**RELATIVE INTENSITY VS. WAVELENGTH(λ_p)

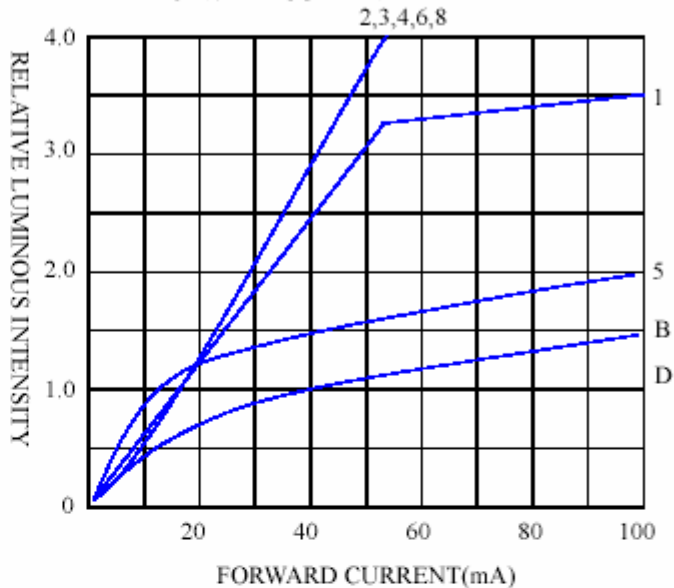
- | | |
|---|----------------------------------|
| (1) GaAsP/GaAs 655nm/Red | (9)- GaAlAs 880nm |
| (2) GaP 568nm/ Yellow Green | (10)-GaAs/GaAs&GaAlAs/GaAs 940nm |
| (3) GaAsP/GaP 585nm/Yellow | (A)- GaN 430nm/Blue |
| (4) GaAsP/GaP 635nm/Orange & Hi-Eff Red | (B)- InGaN 470nm/Blue |
| (5) GaP 700nm/Bright Red | (C)- InGaN 502nm/Ultra Green |
| (6) GaAlAs/GaAs 660nm/Super Red | (D)- InGaN 523nm/Ultra Green |
| (8) GaAsP/GaP 610nm/Super Red | |

SURFACE MOUNT CHIP LED LAMPS**Part Number: IR15-21C/L10****Typical Optical-Electrical Characteristic Curves**◆ **CHARACTERISTICS DIAGRAMS**

FORWARD CURRENT VS. FORWARD VOLTAGE



RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT



FORWARD CURRENT VS. AMBIENT TEMPERATURE

